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Part Number: [0877050021](#)
Status: **Active**
Description: 1.00mm (.039") Pitch DDR-II DIMM Socket, Vertical, Center Keys, 2.67mm (.105") Tail Length, Beige Latches, 0.38µm (15µ") Gold (Au) Plating, with Beveled Metal Pins, 240 Circuits, Lead-Free

Documents:

[3D Model](#) [Product Specification PS-87705-002 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA 1409726
UL E29179

General

Product Family Memory Module Sockets
Series [87705](#)
Comments Latches in Beige Color
Component Type Socket
JEDEC Outline MO-237
Product Name DDR2 DIMM

Physical

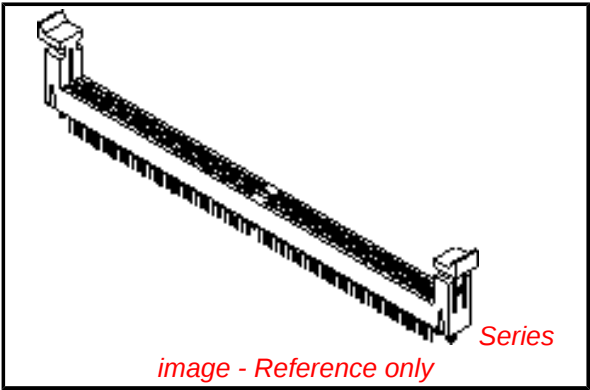
Circuits (Loaded) 240
Color - Resin Black, Natural
Durability (mating cycles max) 25
Entry Angle Vertical (Top Entry)
Flammability 94V-0
Keying to Mating Part Yes
Material - Metal Brass, Phosphor Bronze
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
PC Tail Length (in) 0.105 In
PC Tail Length (mm) 2.67 mm
PCB Retention Yes
PCB Thickness Recommended (in) 0.062 In
PCB Thickness Recommended (mm) 1.60 mm
Packaging Type Tray
Pitch - Mating Interface (in) 0.039 In
Pitch - Mating Interface (mm) 1.00 mm
Plating min: Mating (µin) 15.2
Plating min: Mating (µm) 0.38
Plating min: Termination (µin) 101.6
Plating min: Termination (µm) 2.54
Temperature Range - Operating -10°C to +85°C
Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 0.5A
Voltage - Maximum 30V
Voltage Key 1.8V, Center

Solder Process Data

Duration at Max. Process Temperature (seconds) 5
Lead-free Process Capability SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature 1



EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Not Reviewed
**Halogen-Free
Status**

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series
[87705Series](#)

Mates With
JEDEC standard 1.27mm modules

Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Product Specification	PS-87705-002
Sales Drawing	SD-87705-001

This document was generated on 05/27/2010

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NOTES:

1. MATERIALS

HOUSING - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0
COLOR: BLACK
EJECTOR - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0
COLOR: SEE TABLE
TERMINAL - COPPER ALLOY

2. PLATING - SEE TABLE IN SHEET 5 & 6.

3. CARD SLOT ACCEPTS 1.27±0.10 MM MODULE THICKNESS.
(MEASURED OVER P.C. PADS)

4. RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237.

5. REFER TO PRODUCT SPEC. PS-87705-002 FOR PERFORMANCE
SPECIFICATIONS.

6. PRODUCT SHALL BE PACKED IN TRAY.

7. PRODUCT SHALL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.

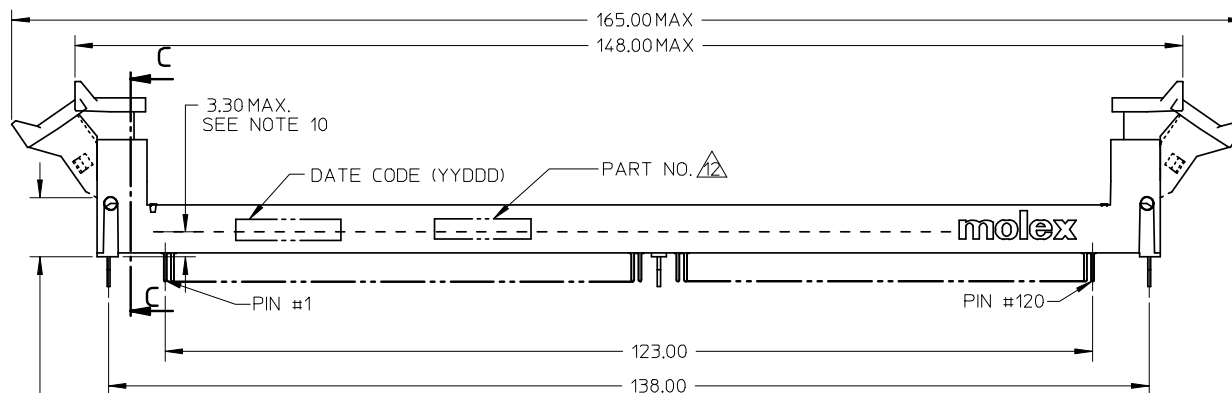
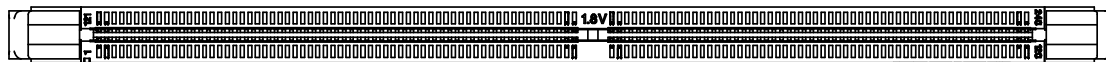
8. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS
MOUNTED ONTO THE PCB WHICH DOES NOT INCLUDE THE LATCH.

9. REFER TO CRITICAL JEDEC INFORMATION FOR SOCKET OUTLINE
PER SO-001.

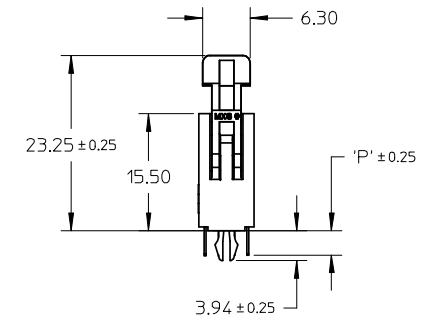
10. DIMM MODULE SEATING PLANE FROM TOP OF PCB.

11. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

△ PART NUMBER SHALL BE MARKED LEGIBLY AS 87705-****



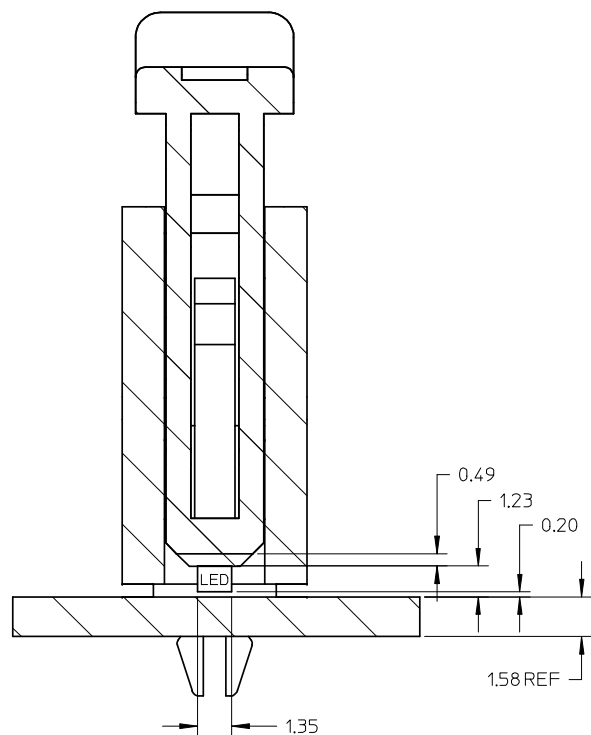
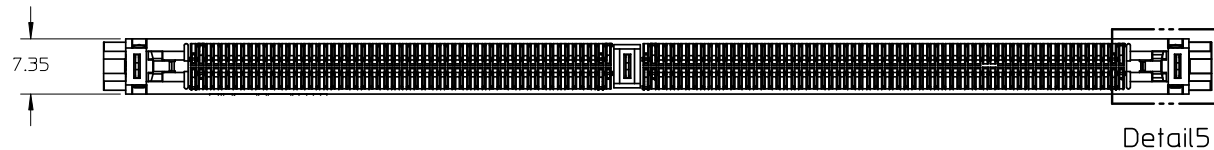
5.00 MIN
LATCH KEEP
OUT AREA



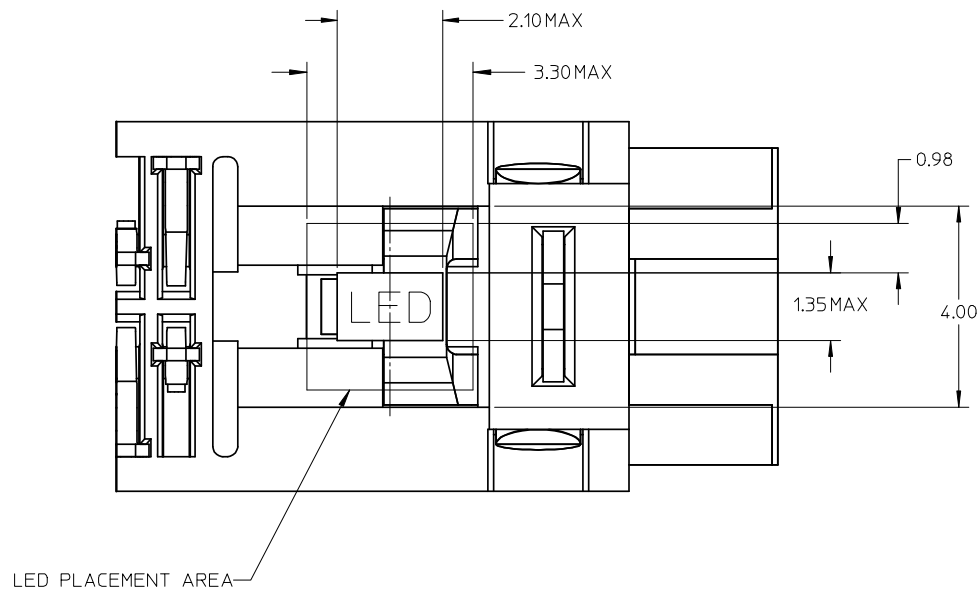
ADD NOTE @SHT4 C1 EC NO: S2008-1044 DRWN:CMTEO 2008/05/15 CHKD:CGTAN 2008/05/15 APPR:SHLENI 2008/05/15 REV		DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
						DRAWN BY CGOH		DATE 2002/05/09	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS (FORKLOCK VERSION) MOLEX INCORPORATED		
						CHECKED BY		DATE 2002/07/22			
						APPROVED BY		DATE 2002/07/23			
D1				mm		INCH		 MOLEX			
				4 PLACES ± --- ± ---		DATE					
				3 PLACES ± --- ± ---		DATE					
				2 PLACES ± 0.20 ± ---		DATE					
				1 PLACE ± --- ± ---		APPROVED BY		DATE			
				ANGULAR ± 5 °		SKTOH		2002/07/23			
						MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-87705-001		1 OF 6	
						SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



SECTION C-C



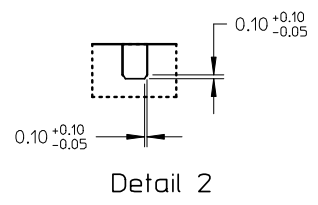
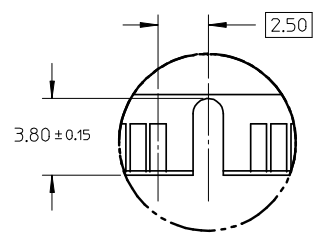
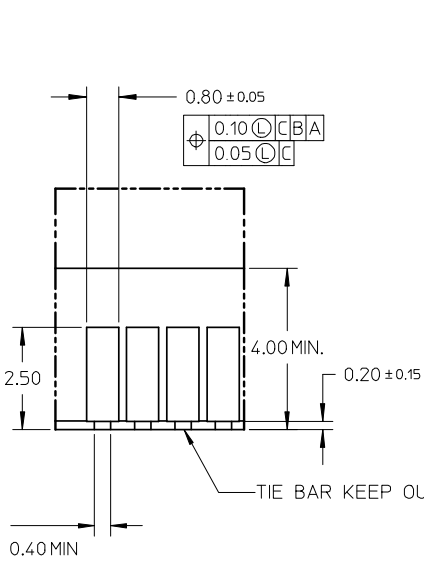
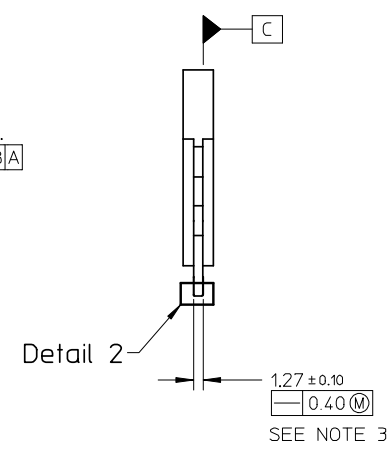
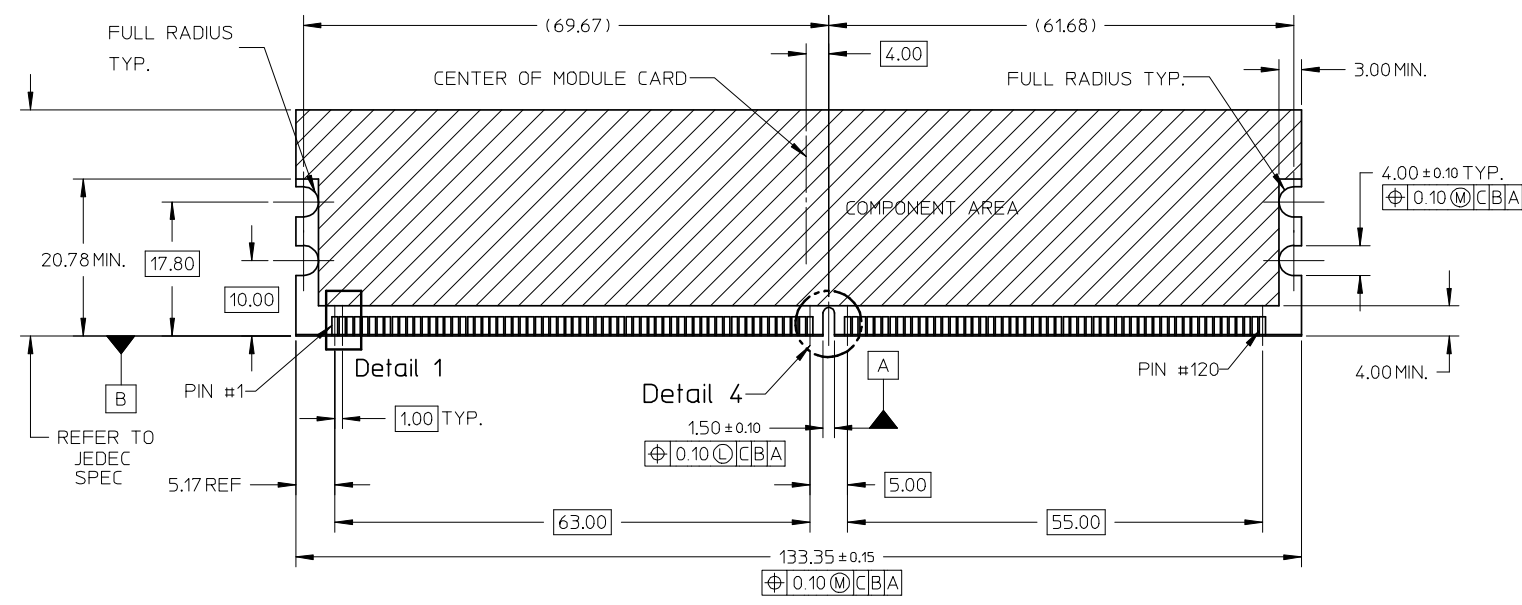
Detail 5

ADD NOTE @SHT 4 C1 EC NO: S2008-1044 2008/05/15 DRWN:CMTEO CHKD:CGTAN 2008/05/15 APPR:SHLENI 2008/05/15			DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	◎ ◻ THIRD ANGLE PROJECTION	
					4 PLACES	mm	INCH	DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION) MOLEX INCORPORATED		
						3 PLACES	± ---	± ---	CHECKED BY DSOH			DATE 2002/07/22
						2 PLACES	± 0.20	± ---	APPROVED BY SKTOH			DATE 2002/07/23
D1					1 PLACE	± ---	± ---	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-87705-001	SHEET NO. 2 OF 6	
					ANGULAR ± 5 °							
					DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

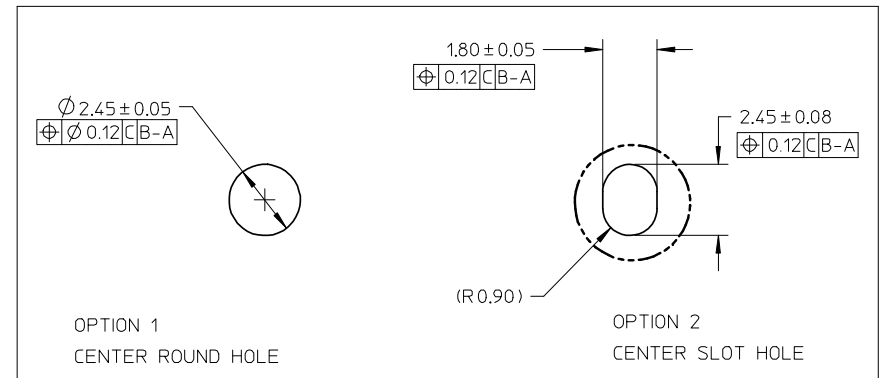
RECOMMENDED MODULE LAYOUT



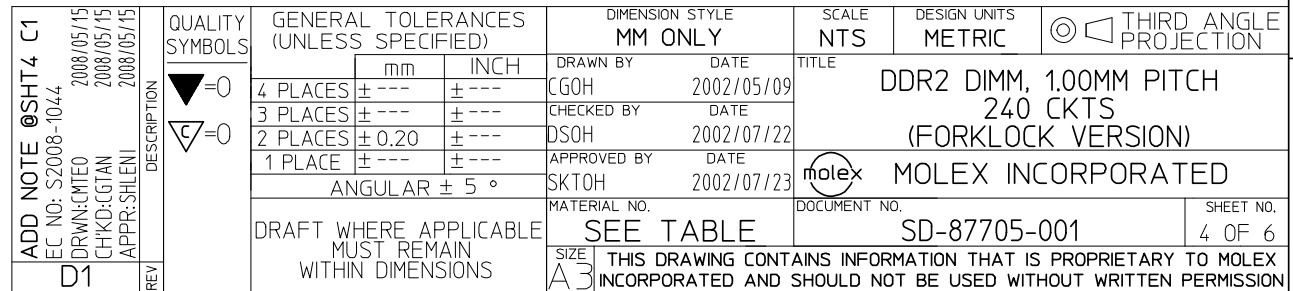
NOTES:
1. MODULE CARD USED FOR TESTS ARE WITH 0.10MM CHAMFER.

ADD NOTE @SHT4 C1 EC NO: S2008-1044 DRWN:CMTE0 2008/05/15 CHKD:GTAN 2008/05/15 APPR:SHENI 2008/05/15 REV			DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
D1				 =0  =0		mm	INCH	DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)  MOLEX INCORPORATED			
					4 PLACES	± ---	± ---	CHECKED BY DSOH	DATE 2002/07/22				
					3 PLACES	± ---	± ---	APPROVED BY SKTOH	DATE 2002/07/23				
					2 PLACES	± 0.20	± ---	MATERIAL NO. SEE TABLE			DOCUMENT NO. SD-87705-001		
					1 PLACE	± ---	± ---	SHEET NO. 3 OF 6					
				ANGULAR ± 5 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

9 8 7 6 5 4 3 2 1



Detail 3



PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR
87705-0021	CENTER (1.8V)	2.67	1.57	0.38uM / 15 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDER TAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE	NATURAL
87705-1021		3.18	2.36		
87705-1053		3.66			
87705-0031		2.67	1.57	0.03uM / 1 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDER TAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE	
87705-1031		3.18	2.36		
87705-0051		2.67	1.57	0.76uM / 30 uIN MIN. GOLD ON CONTACT, 2.54uM/ 100uIN MIN. TIN ON SOLDER TAILS, 1.27uM/ 50uIN MIN. NICKEL UNDERPLATE	
87705-1051		3.18	2.36		

ADD NOTE @SHT 4 C1 EC NO: S2008-1044 DRWN:CMTEO CHKD:CGTAN APPR:SHLEN	2008/05/15 2008/05/15 2008/05/15	DESCRIPTION D1	QUALITY SYMBOLS ▼=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				mm	INCH	DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS (FORKLOCK VERSION)				
				4 PLACES	± ---	± ---	CHECKED BY					DATE 2002/07/22
				3 PLACES	± ---	± ---	DSOH	DATE 2002/07/22	MOLEX INCORPORATED			
				2 PLACES	± 0.20	± ---	APPROVED BY	DATE 2002/07/23				
1 PLACE	± ---	± ---	SKTOH	DATE 2002/07/23	DOCUMENT NO. SD-87705-001		SHEET NO. 5 OF 6					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

